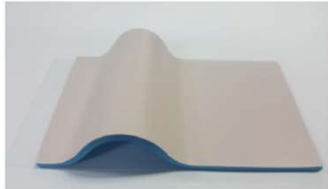
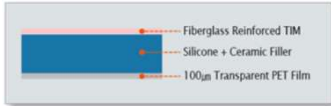


Thermal Interface Material



TP-US20XX



- Very low hardness
- Ultra soft material
- Fiberglass reinforced
- One side naturally tacky

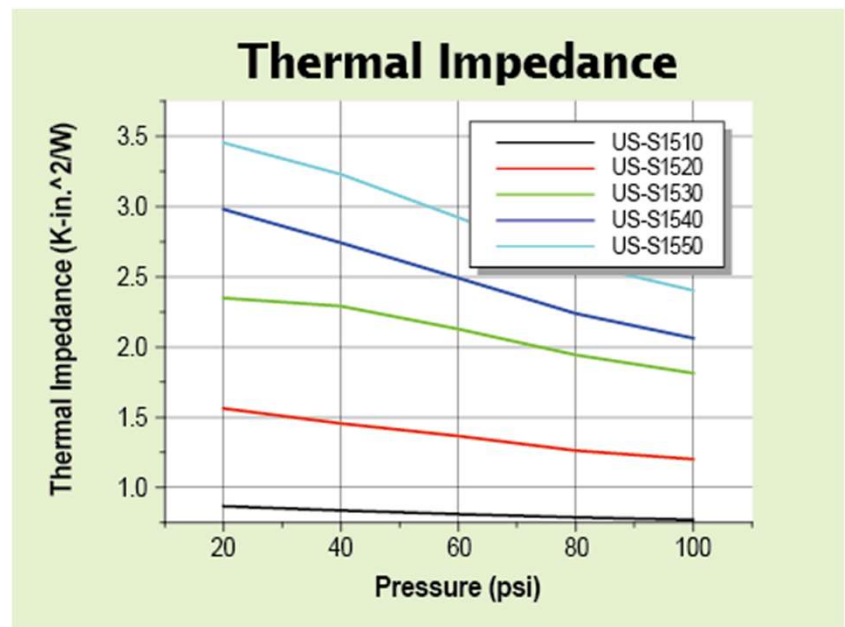
Applications

- Memory modules
- Graphic card
- Processor
- BGA packages

Options

- Available thicknesses: 1.0, 1.5, 2.0, 3.0, 3.5, 4.0, and 5.0mm

Properties	Unit	TP-US15XX
Color		Blue
Thermal Properties		
Thermal Conductivity	W/mK	2.0
Electrical Properties		
Breakdown Voltage $U_{d; ac}$	kV	>5
Volume Resistivity	Ωm	10^{13}
Dielectric Constant ϵ_r		5.5
Mechanical Properties		
Hardness	Shore 00	15
Tensile Strength	MPa (psi)	5 (15)
Young's Modulus	kPa	163
Physical Properties		
Application Temperature	$^{\circ}\text{C}$ ($^{\circ}\text{F}$)	-60 to +200 (-76 to +392)
Density	g/cm^3	2.25
Flame rating	UL-94	V-0
Possible Thickness	mm (inch)	1.0 to 5.0mm (0.04 to 0.2)



The data provide engineering guidance, performance in actual applications should be established through testing.